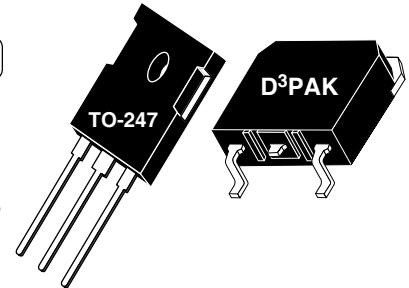
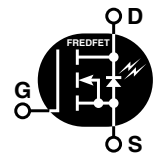


**POWER MOS V®**
**FREDFET**


Power MOS V® is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V® also achieves faster switching speeds through optimized gate layout.

- Fast Recovery Body Diode
- Lower Leakage
- Faster Switching
- Avalanche Energy Rated
- TO-247 or Surface Mount D<sup>3</sup>PAK Package



**MAXIMUM RATINGS**

 All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT6025BVFR_SVFR	UNIT
$V_{DSS}$	Drain-Source Voltage	600	Volts
$I_D$	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	25	Amps
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	100	
$V_{GS}$	Gate-Source Voltage Continuous	±30	Volts
$V_{GSM}$	Gate-Source Voltage Transient	±40	
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	370	Watts
	Linear Derating Factor	2.96	W/°C
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	°C
$T_L$	Lead Temperature: 0.063" from Case for 10 Sec.	300	
$I_{AR}$	Avalanche Current <sup>①</sup> (Repetitive and Non-Repetitive)	25	Amps
$E_{AR}$	Repetitive Avalanche Energy <sup>①</sup>	30	mJ
$E_{AS}$	Single Pulse Avalanche Energy <sup>④</sup>	1300	

**STATIC ELECTRICAL CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0V, I_D = 250\mu A$ )	600			Volts
$R_{DS(on)}$	Drain-Source On-State Resistance <sup>②</sup> ( $V_{GS} = 10V, 12.5A$ )			0.250	Ohms
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = 600V, V_{GS} = 0V$ )			250	$\mu A$
	Zero Gate Voltage Drain Current ( $V_{DS} = 480V, V_{GS} = 0V, T_C = 125^\circ\text{C}$ )			1000	
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 30V, V_{DS} = 0V$ )			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}, I_D = 1mA$ )	2		4	Volts

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

**DYNAMIC CHARACTERISTICS**

**APT6025BFVR\_SVFR**

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V		4300	5160	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		525	735	
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1 MHz		220	330	
Q <sub>g</sub>	Total Gate Charge ③	V <sub>GS</sub> = 10V		185	275	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DD</sub> = 0.5 V <sub>DSS</sub>		23	35	
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		85	125	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = 15V		14	28	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 0.5 V <sub>DSS</sub>		12	28	
t <sub>d(off)</sub>	Turn-off Delay Time	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		55	80	
t <sub>f</sub>	Fall Time	R <sub>G</sub> = 1.6Ω		10	20	

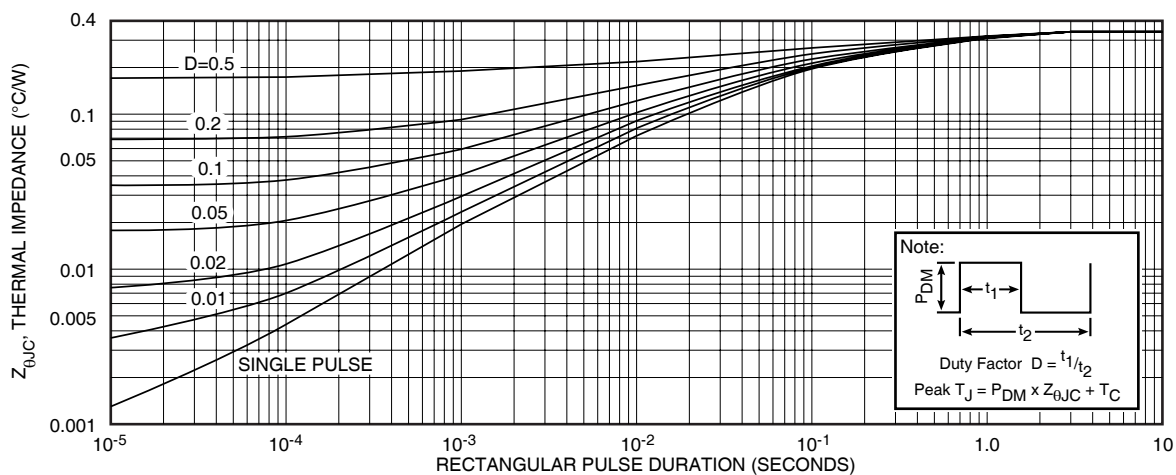
**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I <sub>S</sub>	Continuous Source Current (Body Diode)			25	Amps
I <sub>SM</sub>	Pulsed Source Current ① (Body Diode)			100	
V <sub>SD</sub>	Diode Forward Voltage ② (V <sub>GS</sub> = 0V, I <sub>S</sub> = -I <sub>D</sub> [Cont.])			1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ⑤			15	V/ns
t <sub>rr</sub>	Reverse Recovery Time (I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/dt = 100A/μs)	T <sub>j</sub> = 25°C		205	ns
		T <sub>j</sub> = 125°C		415	
Q <sub>rr</sub>	Reverse Recovery Charge (I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/dt = 100A/μs)	T <sub>j</sub> = 25°C		1.5	μC
		T <sub>j</sub> = 125°C		5.5	
I <sub>RRM</sub>	Peak Recovery Current (I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/dt = 100A/μs)	T <sub>j</sub> = 25°C		13	Amps
		T <sub>j</sub> = 125°C		23	

**THERMAL CHARACTERISTICS**

Symbol	Characteristic	MIN	TYP	MAX	UNIT
R <sub>θJC</sub>	Junction to Case			0.34	°C/W
R <sub>θJA</sub>	Junction to Ambient			40	

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
  - ② Pulse Test: Pulse width < 380 μs, Duty Cycle < 2%
  - ③ See MIL-STD-750 Method 3471
  - ④ Starting T<sub>j</sub> = +25°C, L = 4.16mH, R<sub>G</sub> = 25Ω, Peak I<sub>L</sub> = 25A
  - ⑤ I<sub>S</sub> ≤ I<sub>D</sub> [Cont.], di/dt = 100A/μs, T<sub>j</sub> ≤ 150°C, R<sub>G</sub> = 2.0Ω V<sub>R</sub> = 200V.
- APT Reserves the right to change, without notice, the specifications and information contained herein.**



**FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION**

Typical Performance Curves

APT6025BFVR\_SVFR

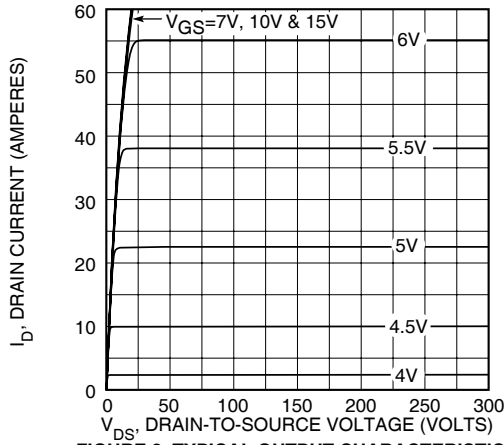


FIGURE 2, TYPICAL OUTPUT CHARACTERISTICS

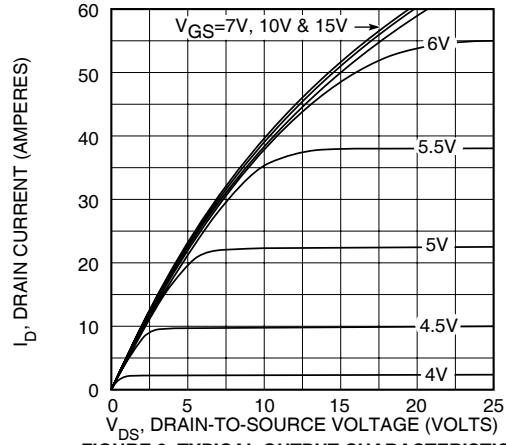


FIGURE 3, TYPICAL OUTPUT CHARACTERISTICS

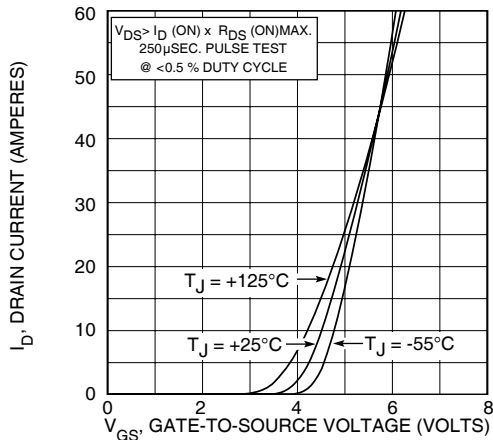


FIGURE 4, TYPICAL TRANSFER CHARACTERISTICS

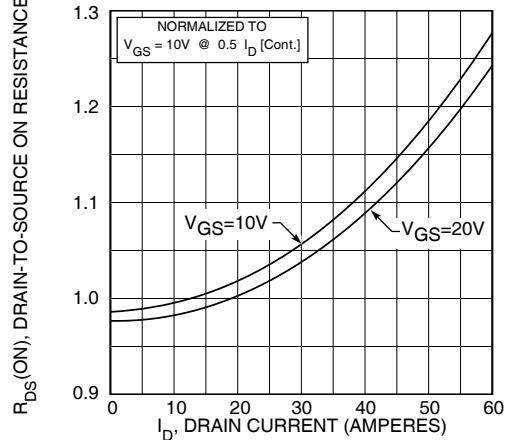


FIGURE 5,  $R_{DS(ON)}$  vs DRAIN CURRENT

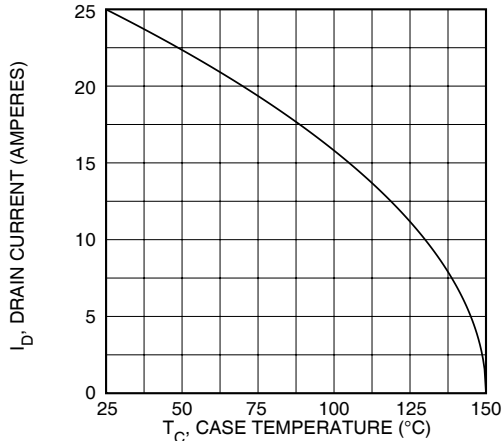


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

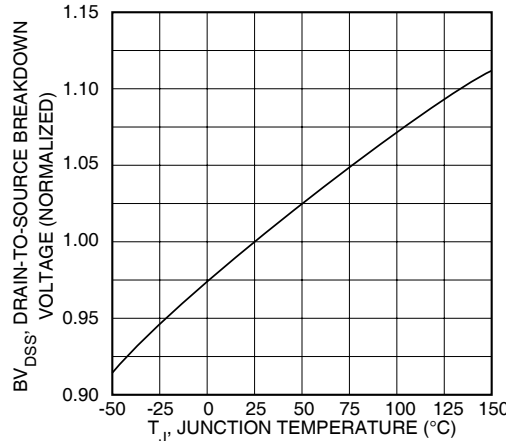


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

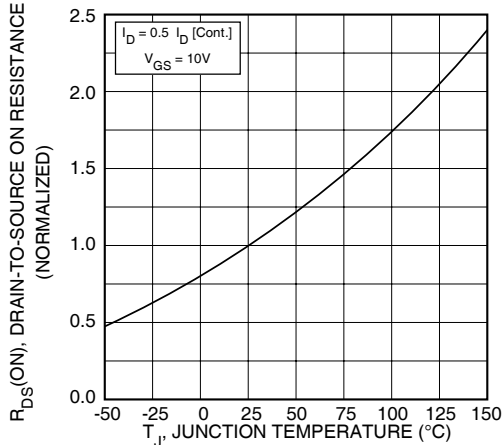


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

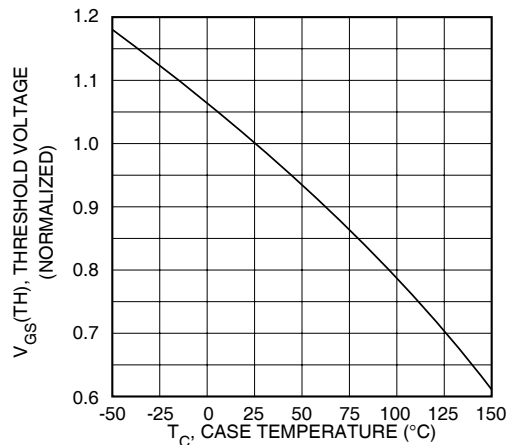


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

## Typical Performance Curves

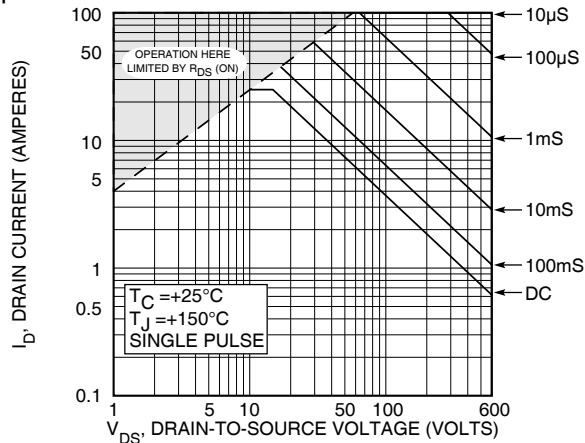


FIGURE 10, MAXIMUM SAFE OPERATING AREA

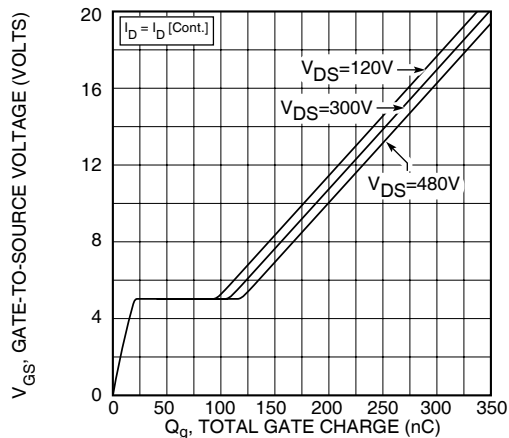


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

## APT6025BFVR\_SVFR

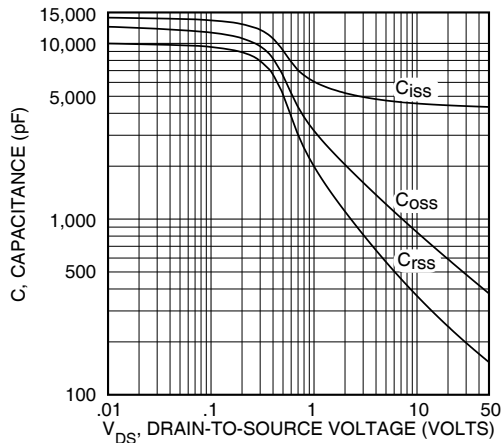


FIGURE 11, TYPICAL CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

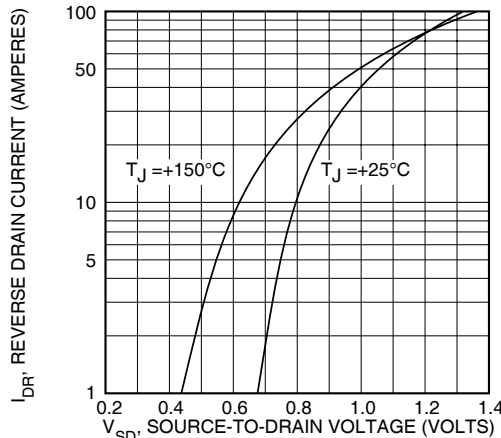
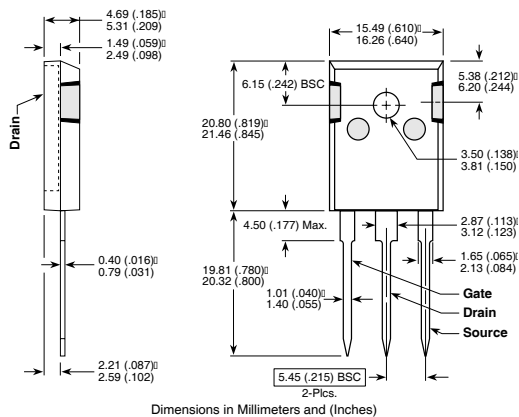


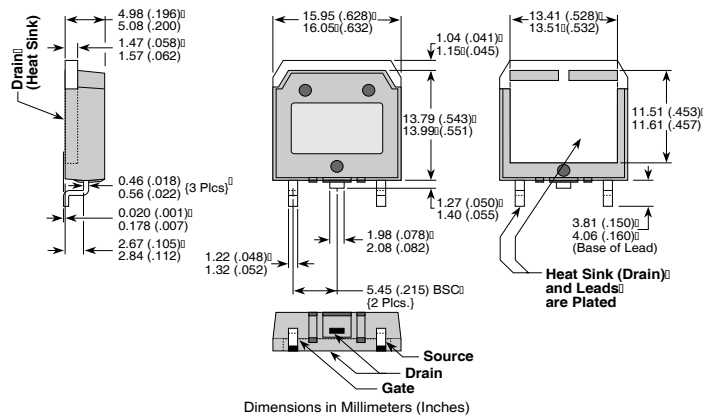
FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

## TO-247 Package Outline



Dimensions in Millimeters and (Inches)

## D<sup>3</sup>PAK Package Outline



Dimensions in Millimeters (Inches)

050-5631 Rev A 1-2005

APT's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. US and Foreign patents pending. All Rights Reserved.